Semiconductor Packaging and Assembly Equipment Market Opportunities by Key Vendors, Segmentation and Forecasts 2020

Analysts forecast the global semiconductor packaging equipment market to grow at a CAGR of 8.04% during the period 2016-2020.

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About Semiconductor Packaging

Semiconductor packaging is carried out to provide extra protection to wafers or substrates. The package casing is made up of materials such as metal, plastic, glass, or ceramic and contains one or more semiconductor electronic components.

Semiconductor packaging offers the following benefits to wafers:
• Prevents corrosion
• Offers protection in case of impact
• Dissipates heat produced in the device
• Secures the contact leads or pins used to plug in the device to its external circuits

Analysts forecast the global semiconductor packaging equipment market to grow at a CAGR of 8.04% during the period 2016-2020.

Covered in this report

The report covers the present scenario and the growth prospects of the global semiconductor packaging equipment market for 2016-2020. To calculate the market size, the report considers the sale of semiconductor packaging equipment to the end-users — OSATs and IDMs.

The market is divided into the following segments based on geography:
• APAC
• Europe
• North America

Global Semiconductor Packaging Equipment Market 2016-2020, has been prepared based on an in-depth market analysis with inputs from industry experts. The report covers the market landscape and its growth prospects over the coming years. The report also includes a discussion of the key vendors operating in this market.

Key vendors
• Applied Materials

• ASM Pacific Technology
• Kulicke and Soffa Industries
• Tokyo Electron Limited
• Tokyo Seimitsu

Other prominent vendors
• ChipMos
• Greatek
• Hua Hong
• Jiangsu Changjiang Electronics Technology
• Lingsen Precision
• Nepes
• Tianshui Huatian
• Unisem
• Ultratech

Market driver
• High demand for polymer adhesive wafer bonding equipment
• For a full, detailed list, view our report

Market challenge
• Fluctuation of foreign exchange rates
• For a full, detailed list, view our report

Market trend
• Growing number of mergers and acquisitions
• For a full, detailed list, view our report

Key questions answered in this report
• What will the market size be in 2020 and what will the growth rate be?
• What are the key market trends?
• What is driving this market?
• What are the challenges to market growth?
• Who are the key vendors in this market space?
• What are the market opportunities and threats faced by the key vendors?
• What are the strengths and weaknesses of the key vendors?

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